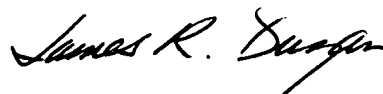


REMARKS

No new matter has been added. The Applicants again request entry of the amendments as set forth in the Appendices hereto prior to examination of the application on the merits.

Respectfully submitted,



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JRD/csw

Enclosures: Version of Specification with Markings to Show Changes Made
 Version of Claims with Markings to Show Changes Made

VERSION OF SPECIFICATION WITH MARKINGS TO SHOW CHANGES MADE

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application is a continuation of application Serial No. 09/569,216, filed May 11, 2000, [~~pending~~] now U.S. Patent 6,337,511 B1, issued January 8, 2002, which is a divisional of application Serial No. 09/176,967, filed October 22, 1998, now U.S. Patent 6,248,611 B1, issued June 19, 2001, which is a continuation of application Serial No. 08/916,977, filed August 14, 1997, now U.S. Patent 5,840,598, issued November 24, 1998.



Serial No.: 10/035,078

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) A semiconductor device comprising:
a lead frame having a plurality of lead fingers thereon, at least one lead finger of said plurality of lead fingers having an attaching surface;
a semiconductor die having an active surface having at least one bond pad thereon configured for electrical connection to said at least one lead finger of said plurality of lead fingers of said lead frame; and
a ~~[non-conductive]~~ nonconductive polymer adhesive selected from ~~[the]~~ a group of adhesives that is tacky and compliant at room temperature, said ~~[non-conductive]~~ nonconductive polymer adhesive applied to one of said attaching surface of said at least one lead finger of said plurality of lead fingers of said lead frame and a portion of said active surface of said semiconductor die for compression therebetween to electrically connect said at least one bond pad of said semiconductor die to said at least one lead finger of said plurality of lead fingers of said lead frame, said ~~[non-conductive]~~ nonconductive polymer adhesive including a first material from ~~[the]~~ a group of copolymers that includes isobutyl compounds and a second material that is from a group of metal oxides.

2. (Amended) The semiconductor device of claim 1 wherein a first portion of said ~~[non-conductive]~~ nonconductive polymer adhesive is isobutyl acetal diphenol copolymer.

3. (Amended) The semiconductor device of claim 1 wherein said ~~[non-conductive]~~ nonconductive polymer adhesive includes [a] said first material from a group of copolymers that includes isobutyl acetal diphenol copolymer and [a] said second material that is from [a] said group of metal oxides that includes titanium dioxide.

4. (Amended) The semiconductor device of claim 3 wherein said ~~[non-conductive]~~ nonconductive polymer adhesive has from about 75 percent to about 95 percent by weight of said isobutyl acetal diphenol copolymer and from about 25 percent to about 5 percent by weight, respectively, of said titanium dioxide.

5. (Amended) A semiconductor device comprising:
a lead frame having a plurality of lead fingers thereon, each lead finger of said plurality of lead fingers having an attaching surface;
a semiconductor die having an active surface having bond pads thereon configured for electrical connection to each said lead finger of said plurality of lead fingers of said lead frame; and
a ~~[non-conductive]~~ nonconductive polymer adhesive selected from ~~[the]~~ a group of adhesives that is tacky and compliant at room temperature and is applicable to a substrate through a stencil, said ~~[non-conductive]~~ nonconductive polymer adhesive being applied to one of said attaching surfaces of said plurality of lead fingers of said lead frame and a portion of said active surface of said semiconductor die for compression therebetween to electrically connect said bond pads of said semiconductor device to said plurality of lead fingers of said lead frame, said ~~[non-conductive]~~ nonconductive polymer adhesive includes a first material from ~~[the]~~ a group of copolymers that includes isobutyl compounds and a second material that is from a group of metal oxides.

6. (Amended) The semiconductor device of claim 5, wherein a first portion of said ~~[non-conductive]~~ nonconductive polymer adhesive is isobutyl acetal diphenol copolymer.

7. (Amended) The semiconductor device of claim 5, wherein said ~~[non-conductive]~~ nonconductive polymer adhesive includes [a] said first material from [a] said group of copolymers that includes isobutyl acetal diphenol copolymer and [a] said second material that is from [a] said group of metal oxides that includes titanium dioxide.

8. (Amended) The semiconductor device of claim 7, wherein said ~~[non-conductive]~~ nonconductive polymer adhesive has from about 75 percent to about 95 percent by weight of said isobutyl acetal diphenol copolymer and from about 25 percent to about 5 percent by weight, respectively, of said titanium dioxide.

9. (Amended) A semiconductor device comprising:
a lead frame having a plurality of lead fingers having attaching surfaces thereon;
a semiconductor die having an active surface having at least one bond pad thereon for electrical connection to at least one lead finger of said plurality of lead fingers of said lead frame;
and
a ~~[non-conductive]~~ nonconductive polymer adhesive which includes a first material from a group of copolymers that includes isobutyl acetal diphenol copolymer and a second material that is from a group of metal oxides that includes titanium dioxide, said ~~[non-conductive]~~ nonconductive polymer adhesive being applied to one of said attaching surfaces of said plurality of lead fingers and a portion of said active surface of said semiconductor die for compression therebetween to connect said semiconductor device to said at least one lead finger of said plurality of lead fingers of said lead frame.

11. (Amended) A semiconductor device comprising:
a lead frame having a plurality of lead fingers thereon, each lead finger of said plurality of lead fingers having an attaching surface thereon;
a semiconductor die having an active surface having a plurality of bond pads thereon configured for electrical connection to said plurality of lead fingers of said lead frame;
and
a ~~[non-conductive]~~ nonconductive polymer adhesive which includes a first material from a group of copolymers that includes isobutyl acetal diphenol copolymer and a second material that is from a group of metal oxides that includes titanium dioxide, said ~~[non-~~

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~~conductive]~~ nonconductive polymer adhesive being applied to one of said attaching surfaces of said lead fingers of said plurality of lead fingers and said active surface of said semiconductor die for compression therebetween to connect said active surface of said semiconductor die to said attaching surfaces of said plurality of lead fingers of said lead frame.